CLAIMS

1. An electronic device sealing resin sheet, comprising a first resin layer and a second resin layer,

wherein between a marked region obtained after laser marking is applied to the first resin layer and a region other than the marked region, a contrast of 20% or more is shown,

wherein the content of the filler in the first resin layer is 76% by volume or less, and

wherein the first resin layer comprises carbon black, and the content of the carbon black in the first resin layer is from 0.1 to 2% by weight.

~~2. The electronic device sealing resin sheet according to claim 1, wherein the content of the filler in the first resin layer is 76% by volume or less.~~

~~3. The electronic device sealing resin sheet according to claim 1 or 2, wherein the first resin layer comprises carbon black, and~~

~~the content of the carbon black in the first resin layer is from 0.1 to 2% by weight.~~

~~4~~2. The electronic device sealing resin sheet according to any one of claims 1 to 3, wherein the first resin layer comprises a dye, and

the content of the dye in the first resin layer is from 0.1 to 2% by weight.

~~53~~. The electronic device sealing resin sheet according to ~~any one of~~ claim~~s~~ 1 or~~to~~ 2~~4~~, wherein the second resin layer is obtained by kneading.

~~64~~. A method for manufacturing an electronic device package, comprising the step of sealing an electronic device with the electronic device sealing resin sheet recited in any one of claims 1 to ~~53~~.

~~75~~. The method for manufacturing an electronic device package according to claim ~~64~~, comprising the step of applying laser marking to the first resin layer after the electronic device is sealed.